

ESDALC6V1Px

Low capacitance Transil[™] arrays for ESD protection

Features

- 2 to 4 unidirectional Transil functions
- Breakdown voltage V_{BR} = 6.1 V min.
- Low leakage current < 100 nA
- Low capacitance (7.5 pF @ 3 V)
- Very small PCB area < 2.6 mm²

Benefits

- High ESD protection level
- High integration

Complies with the following standards

- IEC61000-4-2 level 4
 - 15 kV (air discharge)
 - 8 kV (contact discharge)
- MIL STD 883E-Method 3015-7: class3
 - 25 kV HBM (human body model)

Applications

Where transient overvoltage protection in ESD sensitive equipment is required, such as:

- Computers
- Printers
- Communication systems
- Cellular phone handsets and acessories
- Wireline and wireless telephone sets
- Set-top boxes

Description

The ESDALC6V1Px are monolithic suppressors designed to protect components connected to data and transmission lines against ESD.

These devices clamp the voltage just above the logic level supply for positive transients and to a diode drop below ground for negative transients.

TM: Transil is a trademark of STMicroelectronics



SOT-663

SOT-666IP

Figure 1. ESDALC6V1P3 functional diagram

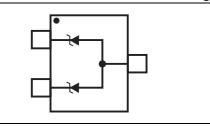
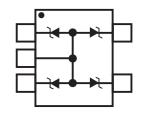
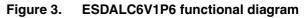
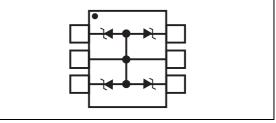


Figure 2. ESDALC6V1P5 functional diagram







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1 Characteristics

Symbol		Value	Unit				
V _{PP} ⁽¹⁾	Peak pulse voltage	IEC 61000-4-2 contact discharge IEC 61000-4-2 air discharge	±8 ±15	kV			
P _{PP}	Peak pulse power $(8/20 \mu s)^{(1)}$	T _j initial = T _{amb}	30	W			
Тj	Junction temperature	150	°C				
T _{stg}	Storage temperature range	-55 to +150	°C				
TL	Maximum lead temperature fo	260	°C				
T _{op}	Operating temperature range -			°C			

Table 1. Absolute ratings ($T_{amb} = 25 \ ^{\circ}C$)

1. For a surge greater than the maximum values, the diode will fail in short-circuit.

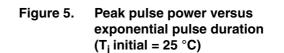
Table 2. Electrical characteristics ($T_{amb} = 25 \ ^{\circ}C$)

					- 20 0)				
Symbol	Parameter					▲ 1			
V _{RM}	Stand-off voltage								
V _{BR}	Breakdown voltage								
V _{CL}	Clamping voltage								
I _{RM}	Leakage current								
I _{PP}	Peak pulse current						I _{RN}	: 	►V
αΤ	Voltage temperature coefficient								
V _F	Forward voltage drop								
С	Capacitance			<u>Slo</u>	pe: 1/R _d	I _{PP}			
R _d	Dynamic resistance				ţ				
	V _{BR} @ I _R		I _{RM} @ V _{RI}	N	R _d	αΤ	С		
Order code	min.	max.		typ.	max.		typ.	typ.	typ.@ 3V
	v	v	mA	nA	μA	v	Ω	10 ⁻⁴ /°C	pF
ESDALC6V1P3 ESDALC6V1P5 ESDALC6V1P6	6.1	7.2	1	10	0.1	3	1.5	4.5	7.5

57

100

Figure 4. Peak power dissipation versus initial junction temperature



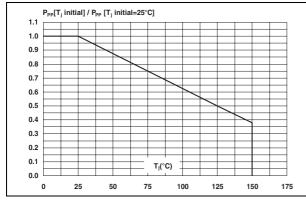
Ppp(W)

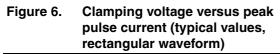
1000

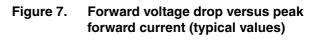
100

10

1







t_p(µs)

10

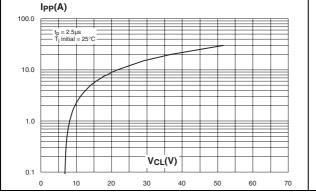


Figure 8. Junction capacitance versus reverse applied voltage (typical values)

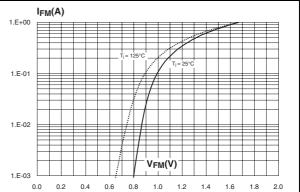


Figure 9. Relative variation of leakage current versus junction temperature (typical values)

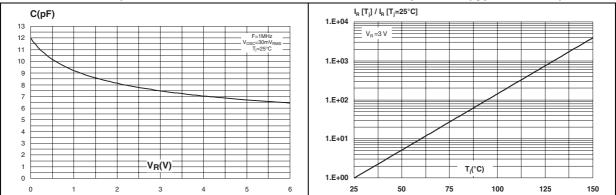


Figure 10. ESD response to IEC 61000-4-2 Figure 11. Analog crosstalk measurement (air discharge 15 kV positive surge)

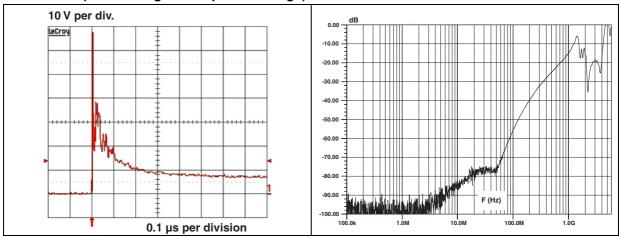
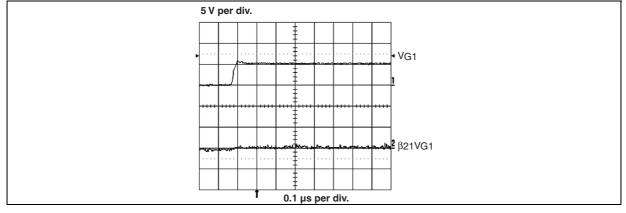
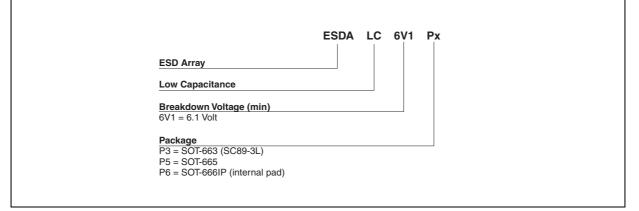


Figure 12. Digital crosstalk test measurement



2 Ordering information scheme

Figure 13. Ordering information scheme





3 Package information

• Epoxy meets UL94, V0

In order to meet environmental requirements, ST offers these devices in ECOPACK[®] packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at *www.st.com*.

Table 3. SOT-663 dimensions

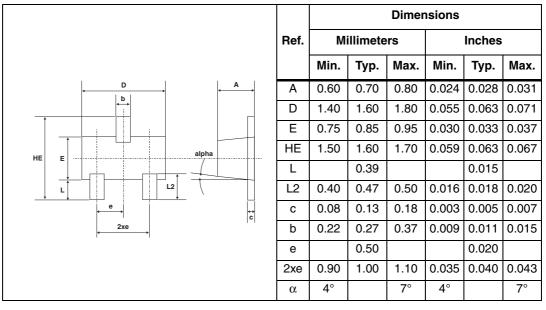
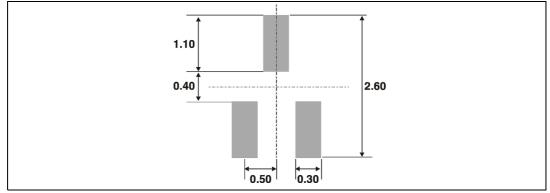


Figure 14. SOT-663 footprint (dimensions in mm)

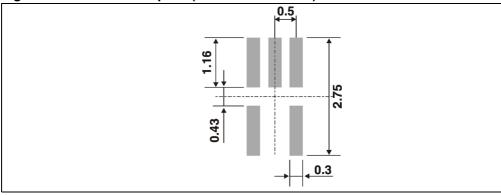


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Table 4. SO 1-665 dimensions					
		Dimensions			
	Ref.	Millimeters		Inches	
		Min.	Max.	Min.	Max.
	А	0.50	0.60	0.020	0.024
$\begin{array}{c} \bullet \\ \bullet $	BP	0.17	0.27	0.007	0.011
	С	0.08	0.18	0.003	0.007
	D	1.50	1.70	0.060	0.067
	E	1.10	1.30	0.043	0.051
	е	1.00		0.040	
	e1	0.50		0.020	
	He	1.50	1.70	0.059	0.067
	Lp	0.10	0.30	0.004	0.012



Figure 15. SOT-665 footprint (dimensions in mm)





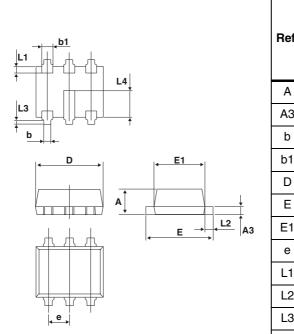
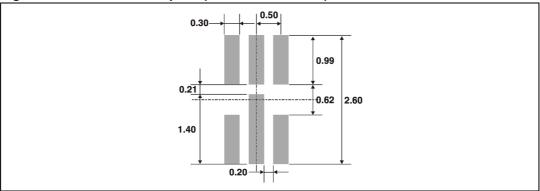


Table 5.	SOT-666IP	dimensions

	Dimensions								
Ref.	Mi	illimete	rs	Inches					
	Min.	Тур.	Max.	Min.	Тур.	Max.			
А	0.45		0.60	0.018		0.024			
A3	0.08		0.18	0.003		0.007			
b	0.17		0.34	0.007		0.013			
b1	0.19	0.27	0.34	0.007	0.011	0.013			
D	1.50		1.70	0.059		0.067			
E	1.50		1.70	0.059		0.067			
E1	1.10		1.30	0.043		0.051			
е		0.50			0.020				
L1		0.19			0.007				
L2	0.10		0.30	0.004		0.012			
L3		0.10			0.004				
L4		0.60			0.024				

Figure 16. SOT-666IP footprint (dimensions in mm)



4 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
ESDALC6V1P3	A2	SOT-663	2.9 mg	3000	Tape and reel
ESDALC6V1P5	A1	SOT-665	2.9 mg	3000	Tape and reel
ESDALC6V1P6 D		SOT-666IP	2.9 mg	3000	Tape and reel

5 Revision history

 Table 7.
 Document revision history

Date Revision		Description of changes		
		ESDALC6V1P3, ESDALC6V1P5, and ESDALC6V1P6 merged and reformatted to current standards.		
23-Aug-2006	2	Table 1 on page 2: Temperature range upgraded to T _j max = 150 °C		
11-Oct-2006 3		Added values for V_{PP} in Table 1.		
23-Apr-2008 4		Reformatted to current standards. Added I _{RM} typical value in <i>Table 2</i> . Update minimum dimension for L2 of SOT-663 in <i>Table 3</i> .		

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